

# N- and P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY							
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)				
N-Channel	60	1.0 at V <sub>GS</sub> = 10 V	0.55				
		1.4 at V <sub>GS</sub> = 4.5 V	0.37				
P-Channel	- 60	2.5 at V <sub>GS</sub> = - 10 V	- 0.3				
r-Channel		3 at V <sub>GS</sub> = - 4.5 V	- 0.2				

#### **FEATURES**

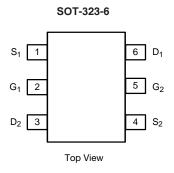
- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> tested
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC

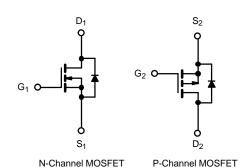


RoHS

### **APPLICATIONS**

- LED Inverter Circuits
- DC/DC Conversion Circuits
- Motor drives
- · Low power load switch





ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		$V_{DS}$	60	- 60	V	
Gate-Source Voltage		$V_{GS}$	± 20		1 V	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	0.55	- 0.3		
	T <sub>C</sub> = 70 °C		0.42	- 0.21		
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	1.7	- 0.9	Α		
Continuous Source Current (Diode Condu	I <sub>S</sub>	0.55	- 0.3			
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	0.73	0.3	W	
	T <sub>C</sub> = 70 °C		0.47	0.192		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

#### Notes

- a. Surface mounted on FR4 board.
- b. Pulse width limited by maximum junction temperature.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static							•	
Drain Course Breakdown Valtage	V	$V_{GS} = 0 \text{ V}, I_D = 10 \mu\text{A}$	N-Ch	60				
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, I}_{D} = -10 \mu\text{A}$	P-Ch	- 60			v	
Oata Thursels ald M. "	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	1		3.0	V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 1		- 3.0		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$	N-Ch			± 100	nA	
adio 200, 200mago	-433	$v_{DS} = 0$ $v$ , $v_{GS} = \pm 10$ $v$	P-Ch			± 100		
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	N-Ch			1		
Zava Cata Valtaga Drain Current	1	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V	P-Ch			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C	N-Ch			10	μA	
		V <sub>DS</sub> = - 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C	P-Ch			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	0.55			Α	
	'D(on)	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V	P-Ch	- 0.3				
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 0.2 A	N-Ch		1.4	2.0		
	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 0.1 A	P-Ch		3.0	4.0		
		$V_{GS} = 10 \text{ V}, I_D = 0.2 \text{ A}$	N-Ch		1.0	1.5	Ω	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 0.1 A	P-Ch		2.5	3.0		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.2 A	N-Ch		195			
		V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 0.1A	P-Ch		150		ms	
_	V <sub>SD</sub>	I <sub>S</sub> = 0.2 A, V <sub>GS</sub> = 0 V	N-Ch		0.8	1.2	1.2 - 1.2	
Diode Forward Voltage <sup>a</sup>		I <sub>S</sub> = - 0.1 A, V <sub>GS</sub> = 0 V	P-Ch		- 0.8	- 1.2		
Dynamic <sup>b</sup>								
Total Cata Chausa	0		N-Ch		1.5			
Total Gate Charge	$Q_g$	Q <sub>g</sub> N-Channel			1.6			
Gate-Source Charge	0	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.2 \text{ A}$	N-Ch		0.3		nC	
Gate-Source Charge	$Q_{gs}$	P-Channel	P-Ch		0.36			
Gate-Drain Charge	Q <sub>ad</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.1 \text{ A}$	N-Ch		0.25			
date Brain Gharge	⊸ga		P-Ch		0.33			
Input Capacitance	C <sub>iss</sub>	N. G.	N-Ch		48.5			
input Capacitance	- 155	N-Channel $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	P-Ch		49			
Output Capacitance	C <sub>oss</sub>	IN-CII			16		pF	
Cutput Cupuolianos		P-Channel	P-Ch		16			
Reverse Transfer Capacitance		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch		8		4	
•	100		P-Ch		8			
Turn-On Time <sup>c</sup>	t <sub>ON</sub>	N-Channel $V_{DD} = 30 \text{ V, R}_{L} = 100 \Omega$	N-Ch		6.5			
	3	$I_D \cong 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	P-Ch		3		ns	
Turn-Off Time <sup>c</sup>	t <sub>OFF</sub>	P-Channel $V_{DD} = -30 \text{ V}, R_1 = 100 \Omega$	N-Ch		13		]	
Turn-Oπ Time°	*OFF	$I_D \cong -0.1 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	P-Ch		13			

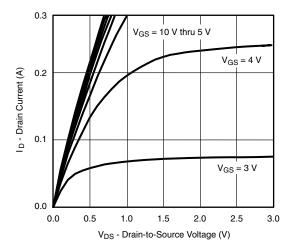
### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

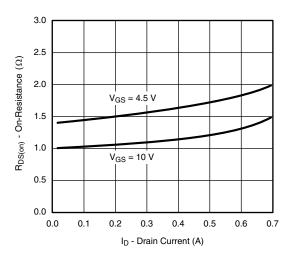
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



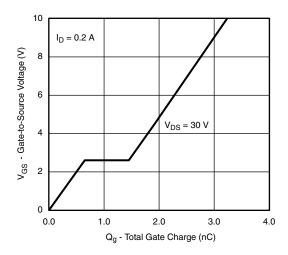
# **N-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}C$ , unless otherwise noted)



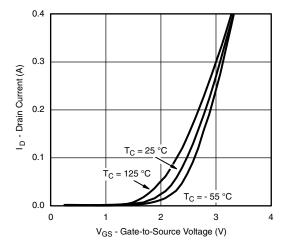
#### **Output Characteristics**



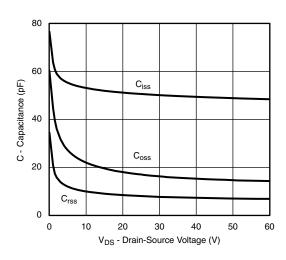
On-Resistance vs. Drain Current



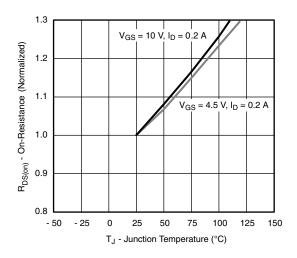
**Gate Charge** 



**Transfer Characteristics Curves vs. Temperature** 



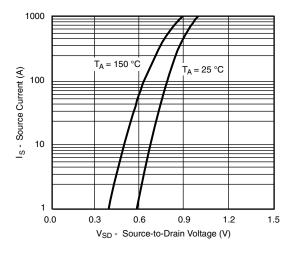
Capacitance



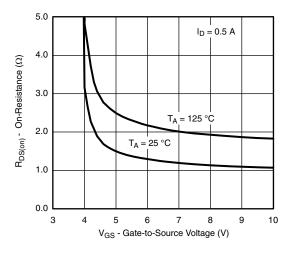
On-Resistance vs. Junction Temperature



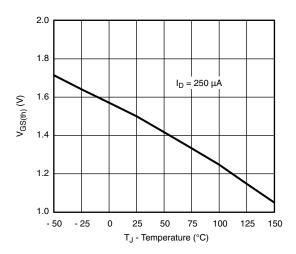
## **N-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}C$ , unless otherwise noted)



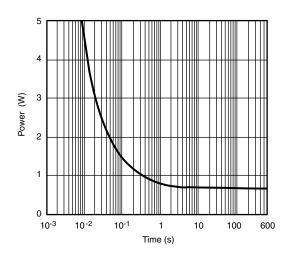
Source-Drain Diode Forward Voltage



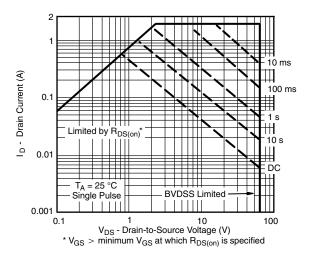
 $R_{DS(on)}\, vs.\, V_{GS}\, vs.\, Temperature$ 



**Threshold Voltage** 



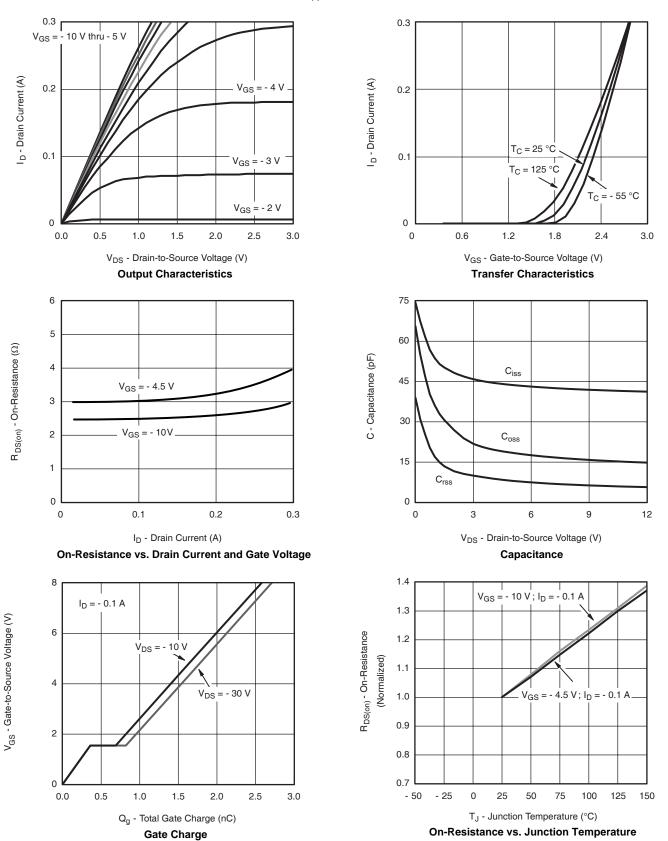
Single Pulse Power



Safe Operating Area

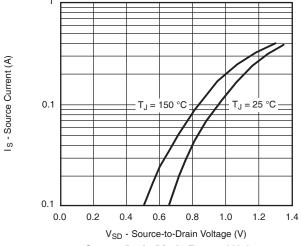


### **P-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

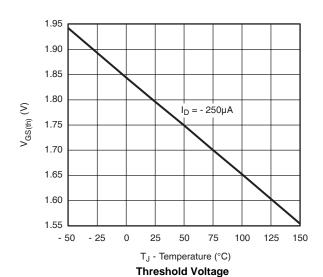




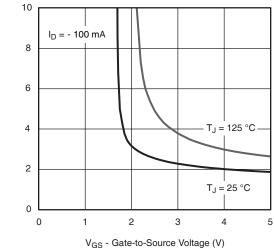
# **P-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



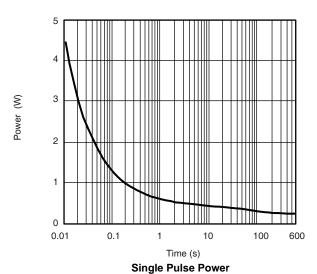
### Source-Drain Diode Forward Voltage

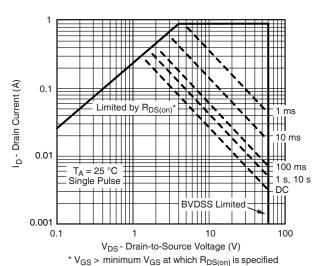


 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - On-Resistance  $(\Omega)$ 



On-Resistance vs. Gate-to-Source Voltage

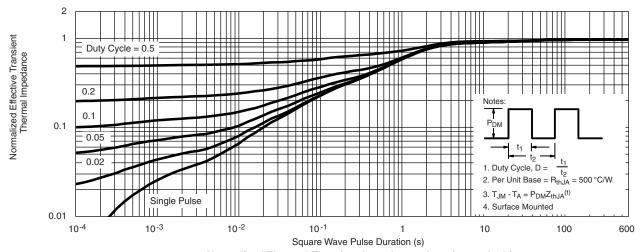




Safe Operating Area, Junction-to-Ambient



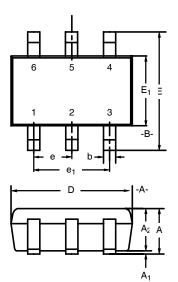
# N- OR P-CHANNEL TYPICAL CHARACTERISTICS ( $T_A = 25~^{\circ}C$ , unless otherwise noted)

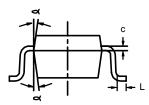


Normalized Thermal Transient Impedance, Junction-to-Ambient





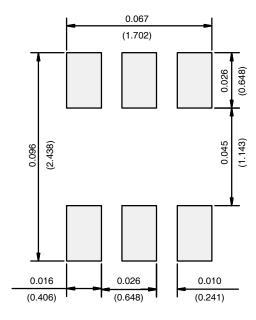




	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	_	0.043
$A_1$	-	-	0.10	-	_	0.004
$A_2$	0.80	-	1.00	0.031	_	0.039
b	0.15	-	0.30	0.006	_	0.012
С	0.10	_	0.25	0.004	_	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC			0.026BSC		
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
Þ	7°Nom			7°Nom		
				,		



### **RECOMMENDED MINIMUM PADS FOR SOT323: 6-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)





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